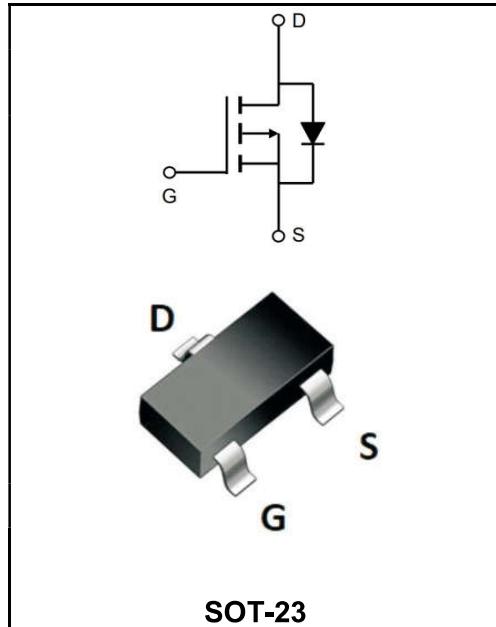


-30V P-CHANNEL ENHANCEMENT MODE MOSFET
MAIN CHARACTERISTICS

I_D	-4.8A
V_{DSS}	-30V
$R_{DS(on)}\text{-typ}(@V_{GS}=10V)$	< 50mΩ (Type: 40 mΩ)
$R_{DS(on)}\text{-typ}(@V_{GS}=4.5V)$	< 55mΩ (Type: 45 mΩ)


Application

- ◆ Battery protection
- ◆ Load switch
- ◆ Uninterruptible power supply

Product Specification Classification

Part Number	Package	Marking	Pack
YFW3401A	SOT-23	A19T	3000PCS/Tape

Maximum Ratings at $T_c=25^\circ C$ unless otherwise specified

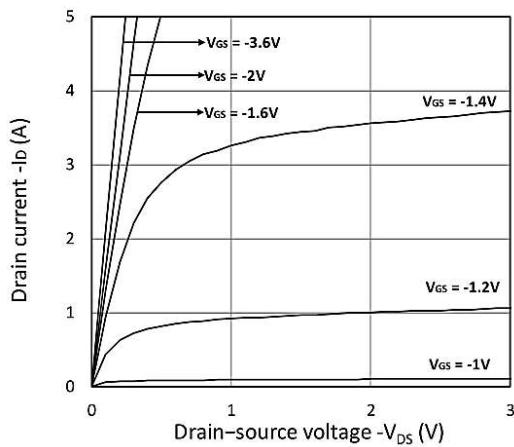
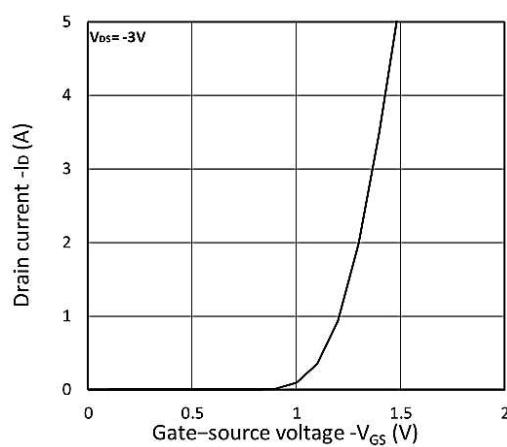
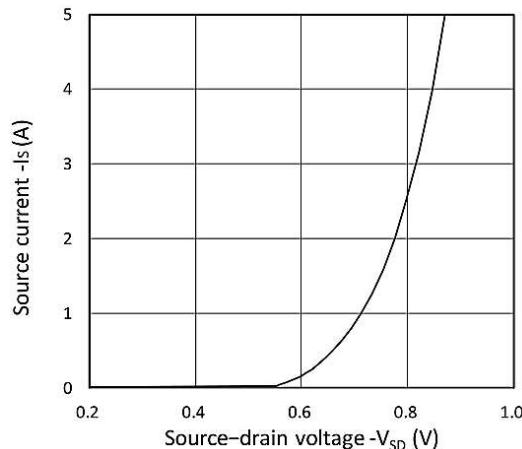
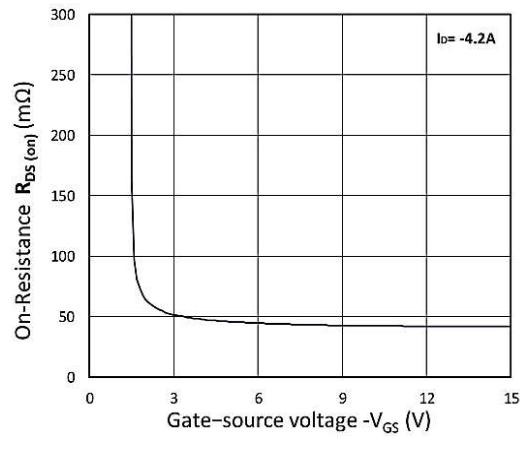
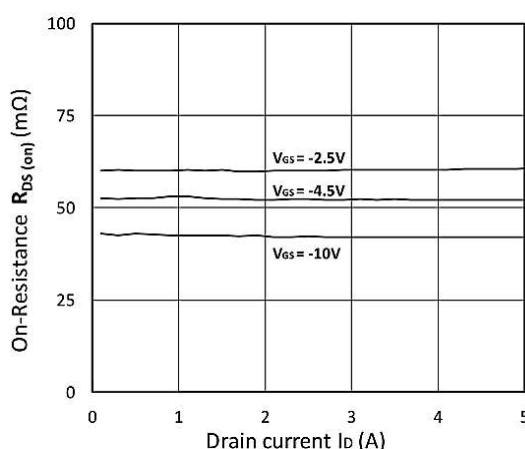
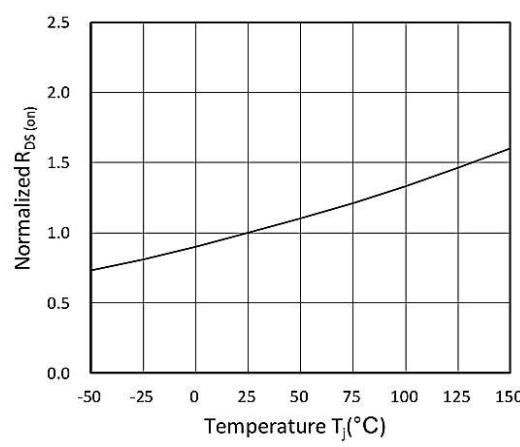
Characteristics	Symbols	Value	Units
Drain-Source Voltage	V_{DS}	-30	V
Gate - Source Voltage	V_{GS}	± 12	V
Continuous Drain Current, $V_{GS} @ -10V^1$ @ $T_c=25^\circ C$	I_D	-4.8	A
Continuous Drain Current, $V_{GS} @ -10V^1$ @ $T_c=100^\circ C$	I_D	-3.3	A
Pulsed Drain Current ^{note1}	I_{DM}	-20.4	A
Power Dissipation $T_A=25^\circ C$	P_D	2.15	W
Thermal Resistance Junction-Ambient ¹	$R_{\theta JA}$	125	°C/W
Thermal Resistance Junction-Case ¹	$R_{\theta JC}$	104	°C/W
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150	°C

Maximum Ratings at $T_c=25^\circ\text{C}$ unless otherwise specified

Characteristics	Test Condition	Symbols	Min	Typ	Max	Units
Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$, $I_D=-250\mu\text{A}$	$\mathbf{V(BR)DSS}$	-30	-34	-	V
Zero Gate Voltage Drain Current	$V_{DS}=-30\text{V}$, $V_{GS}=0\text{V}$	I_{DSS}	-	-	1	μA
Gate to Body Leakage Current	$V_{GS}=\pm20\text{V}$, $V_{DS}=0\text{V}$	I_{GSS}	-	-	±100	nA
Gate Threshold Voltage	$V_{DS}=V_{GS}$, $I_D=-250\mu\text{A}$	$V_{GS(\text{th})}$	-0.5	-1.0	-1.5	V
Static Drain-Source on-Resistance note2	$V_{GS}=-10\text{V}$, $I_D=-5\text{A}$	$R_{DS(\text{ON})}$	-	40	50	$\text{m}\Omega$
	$V_{GS}=-4.5\text{V}$, $I_D=-4\text{A}$		-	45	55	
	$V_{GS}=-2.5\text{V}$, $I_D=-1\text{A}$		-	55	80	
Input Capacitance	$V_{DS}=-15\text{V}$ $V_{GS}=0\text{V}$ $f=1\text{MHz}$	C_{iss}	-	745	-	pF
Output Capacitance		C_{oss}	-	70	-	
Reverse Transfer Capacitance		C_{rss}	-	57	-	
Total Gate Charge	$V_{DS}=-15\text{V}$ $V_{GS}=-10\text{V}$ $I_D=-5.1\text{A}$	Q_g	-	8	-	nC
Gate-Source Charge		Q_{gs}	-	1.8	-	
Gate-Drain("Miller") Charge		Q_{gd}	-	2.7	-	
Turn-on delay time	$V_{DD}=-15\text{V}$ $V_{GS}=-10\text{V}$ $I_D=-1\text{A}$ $R_{GEN}=2.5\Omega$	$t_{d(on)}$	-	7	-	ns
Turn-on Rise Time		T_r	-	3	-	
Turn-Off Delay Time		$t_{d(OFF)}$	-	30	-	
Turn-Off Fall Time		t_f	-	12	-	
Maximum Continuous Drain to Source Diode Forward Current		I_s	-	-	-4.8	A
Maximum Pulsed Drain to Source Diode Forward Current		I_{SM}	-	-	-16.4	A
Drain to Source Diode Forward Voltage	$V_{GS}=0\text{V}$, $I_s=-5.1\text{A}$	V_{SD}	-	-0.8	-1.2	V

Note :

1. The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
2. The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
3. The power dissipation is limited by 150°C junction temperature
4. The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.

Ratings and Characteristic Curves
Typical Characteristics

Figure 1. Output Characteristics

Figure 2. Transfer Characteristics

Figure 3. FORWARD Characteristics of Reverse

Figure 4. RDS(ON) vs. VGS

Figure 5. RDS(ON) vs. ID

Figure 6. Normalized RDS(on) vs. Temperature

Ratings and Characteristic Curves

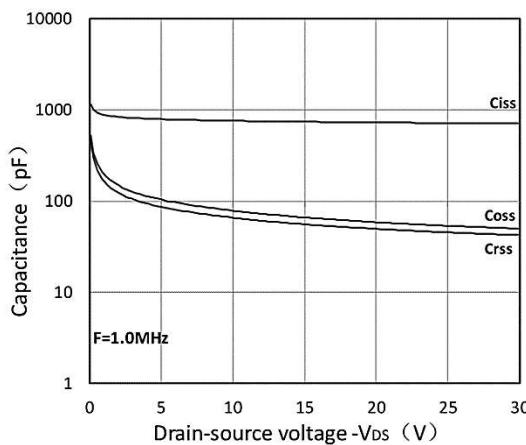


Figure 7. Capacitance Characteristics

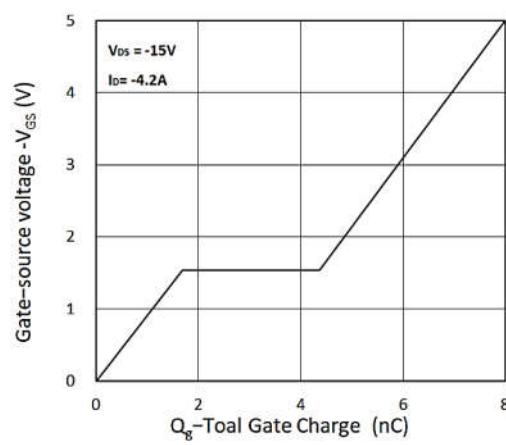


Figure 8. Gate Charge Characteristics

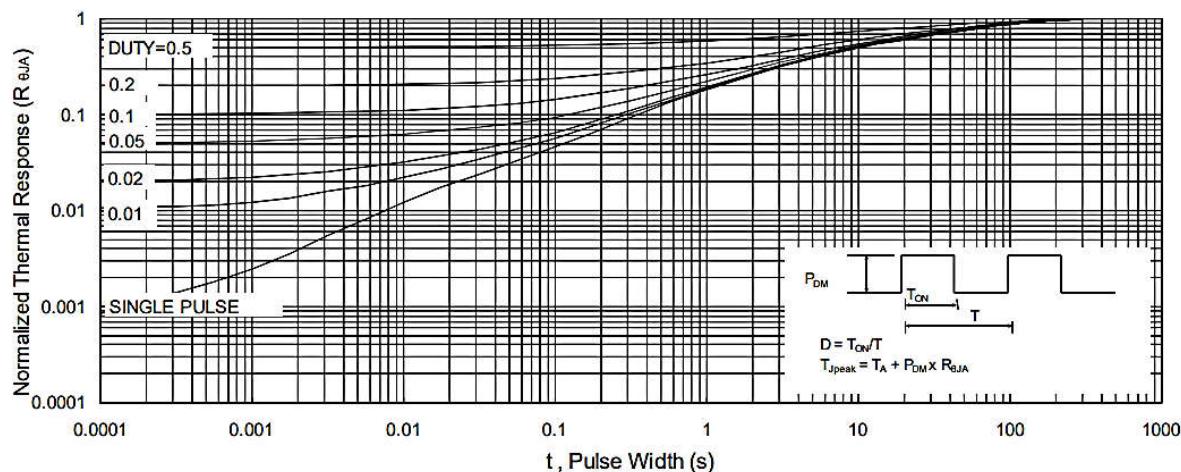


Figure 9 Normalized Maximum Transient Thermal Impedance

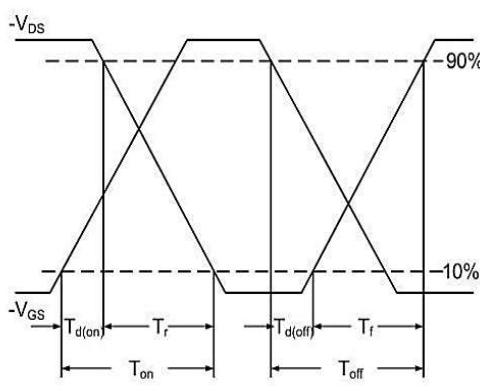


Figure 10 Switching Time Waveform

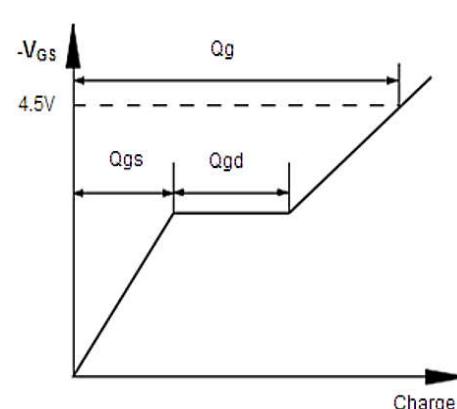
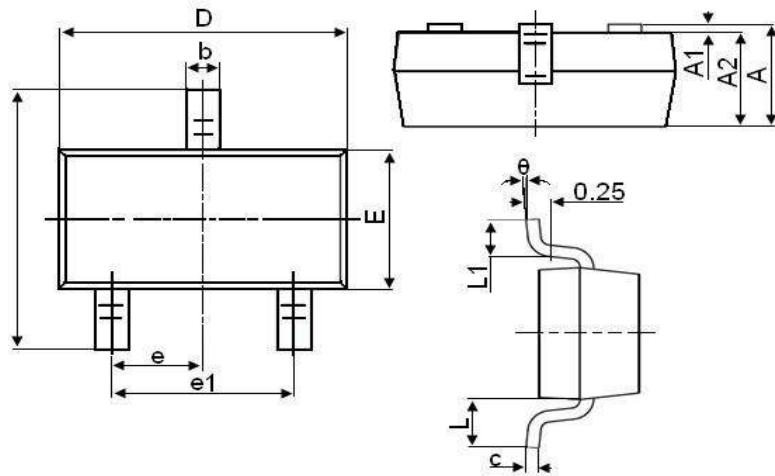


Figure 11 Gate Charge Waveform

Package Outline Dimensions Millimeters

SOT-23



Symbol	Dimensions in Millimeters	
	MIN.	MAX.
A	0.900	1.150
A1	0.000	0.100
A2	0.900	1.050
b	0.300	0.500
c	0.080	0.150
D	2.800	3.000
E	1.200	1.400
E1	2.250	2.550
e	0.950TYP	
e1	1.800	2.000
L	0.550REF	
L1	0.300	0.500
θ	0°	8°